

THAT WHICH IS CLAIMED IS:

1. A method for forming a protective package (11a) made out of plastic material for an electronic device integrated on semiconductor, and comprising an electronic circuit (13) that can be at least partially
5 activated from the outside of the protective package (11a) and that is to be encapsulated in its turn in said protective package (11a), characterized in that:
- it provides the use of a mold (10), comprising a half-mold (11) having a lug (17) projecting towards the
10 inside of the mold, and comprising an end having an element (17) that can be elastically deformed and that abuts in pressing contact against at least one portion of the integrated circuit (13);
 - it injects the resin in the mold so that said
15 protective package has a hole aligned with said portion of said electronic circuit.

2. A method according to claim 1, characterized in that said element 17, which can be elastically deformed, is pressure pressed against the electronic circuit (13).

3. A method according to claim 2 characterized in that said element (17), which can be elastically deformed, abuts in pressing contact against at least a border portion of the integrated circuit
5 (13).

4. A method according to any of the previous claims, characterized in that it comprises the following phases:
- positioning the integrated circuit (13) in the half-mold (15), including said element (17), which can be elastically deformed;
 - having a force acting on a surface of said element

(17), which can be elastically deformed, so that the opposite surface of said element (17) is pressed
10 against at least one portion of the integrated circuit.

5. A mold (10) for molding a plastic protective package (11a) encapsulating an integrated electronic circuit (13), that can be at least partially activated from the outside of said protective package
5 (11a), the mold being formed by a couple of half molds (14, 15) which are laid one on the other to form a space (11) for containing the integrated circuit, characterized in that a half-mold (15) has a lug (17) projecting substantially towards by said electronic
10 circuit (13), said lug being provided with an element (17), which can be elastically deformed, abutting in pressing contact against at least a portion of the electronic circuit (13) during the molding phase.

6. A mold (10) for molding a protective package (11a) according to claim 5, characterized in that said element (17), which can be elastically deformed, is a membrane.

7. A mold (10) for molding a protective package (11a) according to claim 5, characterized in that said membrane (17), along a first membrane surface, is in pressing contact against the electronic
5 circuit, and a fluid acts on the opposite surface, stressing said membrane (17) against the electronic circuit (13).